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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4/A
7/25/29/03

In re Application of)	
Gary B. Hughes et al.)	GAU: 1734
Ser. No. 09/853,125)	Examiner:
Filed: May 9, 2001)	George Koch
For: FABRICATION METHOD FOR ADHESIVE)	
PRESSURE BONDING TWO COMPONENTS)	
TOGETHER WITH CLOSED-LOOP CONTROL))	

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend this application as follows:

IN THE CLAIMS:

Enter the following claims to replace the previously submitted claims of the same respective number:

6. (Amended) The method of claim 1, wherein the step of providing a first component and a second component includes the steps of providing a sensor chip assembly as the first component.

7. (Amended) The method of claim 1, wherein the step of providing a first

A1